



# STP20N20

## STF20N20 - STD20N20

N-CHANNEL 200V - 0.10Ω - 18A TO-220/TO-220FP/DPAK  
LOW GATE CHARGE STripFET™ II MOSFET

Table 1: General Features

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>d</sub>	P <sub>TOT</sub>
STD20N20	200 V	< 0.125 Ω	18 A	90 W
STF20N20	200 V	< 0.125 Ω	18 A	25 W
STP20N20	200 V	< 0.125 Ω	18 A	90 W

- TYPICAL R<sub>DS(on)</sub> = 0.10 Ω
- EXCEPTIONAL dv/dt CAPABILITY
- LOW GATE CHARGE
- 100% AVALANCHE TESTED

### DESCRIPTION

This MOSFET series realized with STMicroelectronics unique STripFET process has specifically been designed to minimize input capacitance and gate charge. It is therefore suitable as primary switch in advanced high-efficiency isolated DC-DC converters.

### APPLICATIONS

- HIGH CURRENT SWITCHING APPLICATIONS
- HIGH EFFICIENCY DC-DC CONVERTERS
- PRIMARY SIDE SWITCH

Figure 1: Package

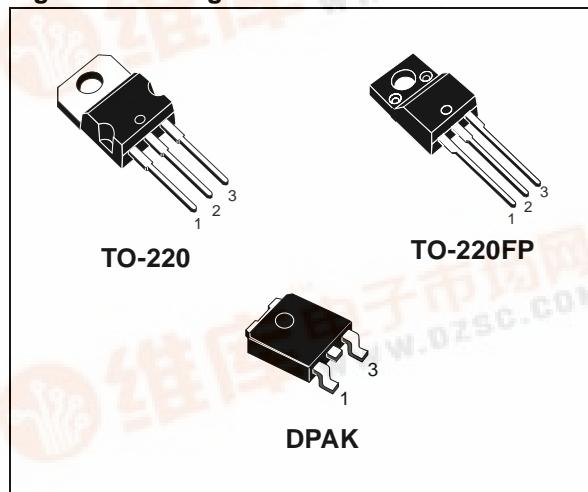


Figure 2: Internal Schematic Diagram

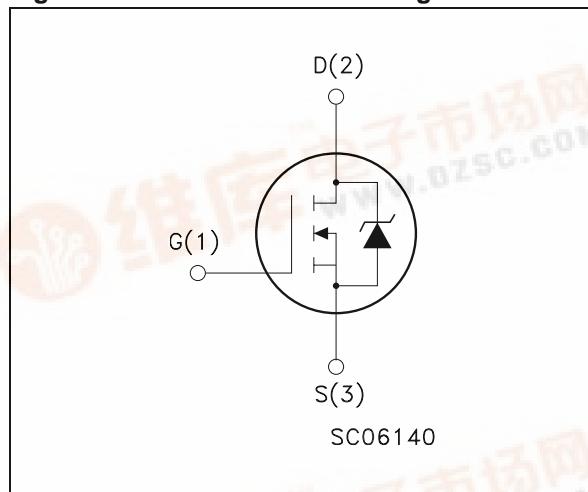


Table 2: Order Codes

SALES TYPE	MARKING	PACKAGE	PACKAGING
STD20N20T4	D20N20	DPAK	TAPE & REEL
STF20N20	F20N20	TO-220FP	TUBE
STP20N20	P20N20	TO-220	TUBE

## STP20N20 - STF20N20 - STD20N20

**Table 3: Absolute Maximum ratings**

Symbol	Parameter	Value		Unit
		TO-220/DPAK	TO-220FP	
$V_{DS}$	Drain-source Voltage ( $V_{GS} = 0$ )	200		V
$V_{DGR}$	Drain-gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	200		V
$V_{GS}$	Gate- source Voltage	$\pm 20$		V
$I_D$	Drain Current (continuous) at $T_C = 25^\circ\text{C}$	18		A
$I_D$	Drain Current (continuous) at $T_C = 100^\circ\text{C}$	11		A
$I_{DM} (\bullet)$	Drain Current (pulsed)	72		A
$P_{TOT}$	Total Dissipation at $T_C = 25^\circ\text{C}$	90	25	W
	Derating Factor	0.72	0.2	W/ $^\circ\text{C}$
$dv/dt$ (1)	Peak Diode Recovery voltage slope	15		V/ns
$T_j$ $T_{stg}$	Operating Junction Temperature Storage Temperature	-50 to 150		$^\circ\text{C}$

(•) Pulse width limited by safe operating area

(1)  $I_{SD} \leq 18\text{A}$ ,  $di/dt \leq 400\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$

**Table 4: Thermal Data**

		TO-220	DPAK	TO-220FP	
$R_{thj-case}$	Thermal Resistance Junction-case Max	1.38	1.38	5	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal Resistance Junction-ambient Max	62.5	50(#)	62.5	$^\circ\text{C/W}$
$T_I$	Maximum Lead Temperature For Soldering Purpose	300			$^\circ\text{C}$

(#) When mounted on 1inch<sup>2</sup> FR-4, 2 Oz copper board.

**Table 5: Avalanche Characteristics**

Symbol	Parameter	Max Value	Unit
$I_{AR}$	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max)	18	A
$E_{AS}$	Single Pulse Avalanche Energy (starting $T_j = 25^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	110	mJ

## ELECTRICAL CHARACTERISTICS ( $T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)

**Table 6: On/Off**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0$	200			V
$I_{DSS}$	Zero Gate Voltage Drain Current ( $V_{GS} = 0$ )	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating}$ , $T_C = 125^\circ\text{C}$			1 10	$\mu\text{A}$ $\mu\text{A}$
$I_{GSS}$	Gate-body Leakage Current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10\text{V}$ , $I_D = 10\text{ A}$		0.10	0.125	$\Omega$

**ELECTRICAL CHARACTERISTICS (CONTINUED)**

**Table 7: Dynamic**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs}$ (1)	Forward Transconductance	$V_{DS} = 25 \text{ V}$ , $I_D = 10 \text{ A}$		13		S
$C_{iss}$ $C_{oss}$ $C_{rss}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25\text{V}$ , $f = 1 \text{ MHz}$ , $V_{GS} = 0$		940 197 30		pF pF pF
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	Turn-on Delay Time Rise Time Turn-off Delay Time Fall Time	$V_{DD} = 100 \text{ V}$ , $I_D = 10 \text{ A}$ , $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$ (see Figure 17)		15 30 40 10		ns ns ns ns
$Q_g$ $Q_{gs}$ $Q_{gd}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 160\text{V}$ , $I_D = 20 \text{ A}$ , $V_{GS} = 10\text{V}$ (see Figure 20)		28 5.6 14.5	39	nC nC nC

**Table 8: Source Drain Diode**

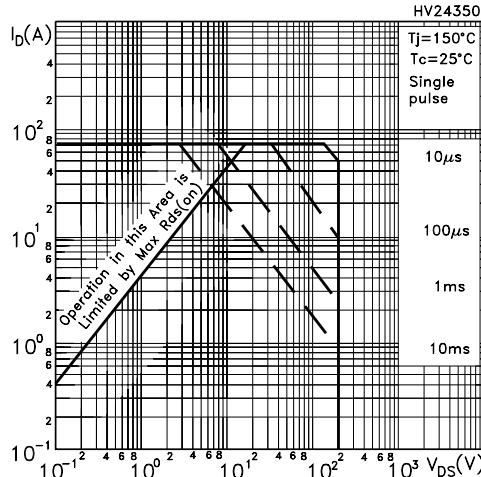
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{SD}$ $I_{SDM}$ (2)	Source-drain Current Source-drain Current (pulsed)				18 72	A A
$V_{SD}$ (1)	Forward On Voltage	$I_{SD} = 20 \text{ A}$ , $V_{GS} = 0$			1.6	V
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 20 \text{ A}$ , $di/dt = 100\text{A}/\mu\text{s}$ $V_{DD} = 50\text{V}$ , $T_j = 25^\circ\text{C}$ (see Figure 18)		155 775 10		ns nC A
$t_{rr}$ $Q_{rr}$ $I_{RRM}$	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 20 \text{ A}$ , $di/dt = 100\text{A}/\mu\text{s}$ $V_{DD} = 50\text{V}$ , $T_j = 150^\circ\text{C}$ (see Figure 18)		183 1061 11.6		ns nC A

(1) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

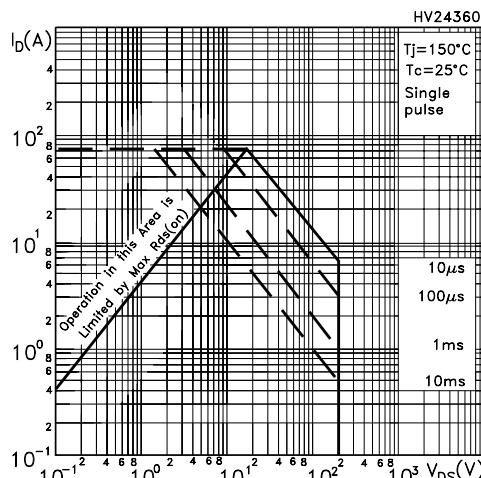
(2) Pulse width limited by safe operating area.

## STP20N20 - STF20N20 - STD20N20

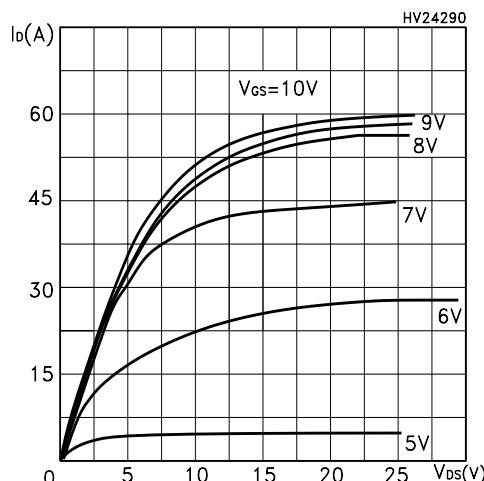
**Figure 3: Safe Operating Area For TO-220/DPAK**



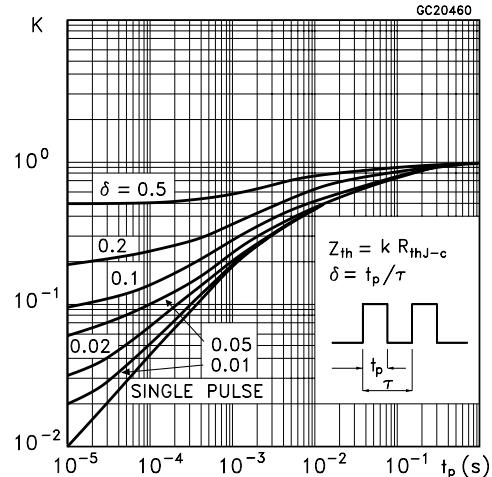
**Figure 4: Safe Operating Area For TO-220FP**



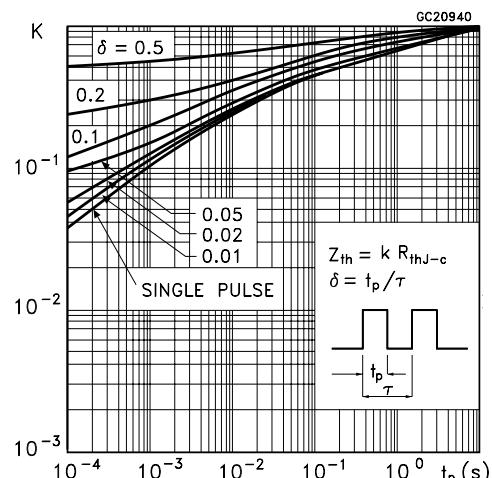
**Figure 5: Output Characteristics**



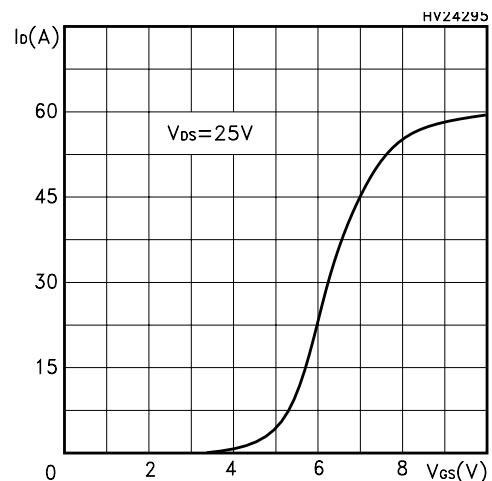
**Figure 6: Thermal Impedance For TO-220/DPAK**



**Figure 7: Thermal Impedance For TO-220FP**

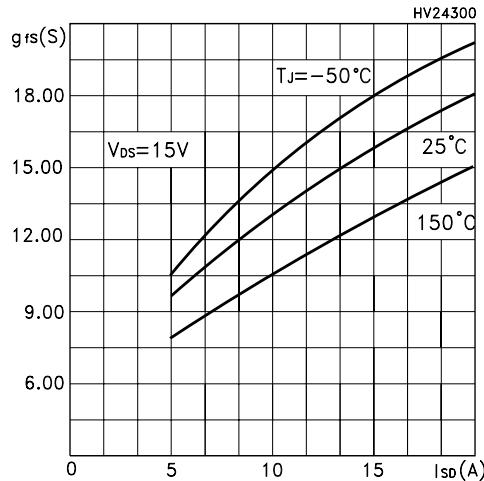


**Figure 8: Transfer Characteristics**

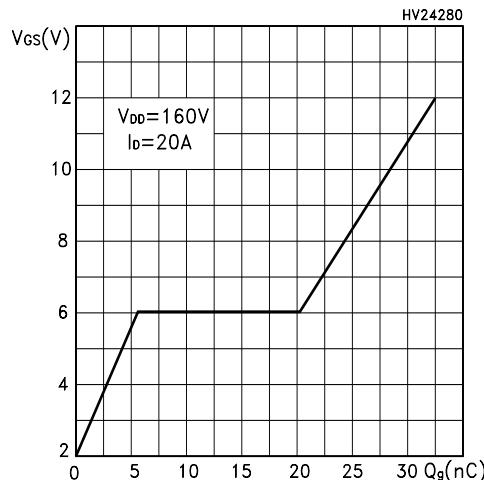


## STP20N20 - STF20N20 - STD20N20

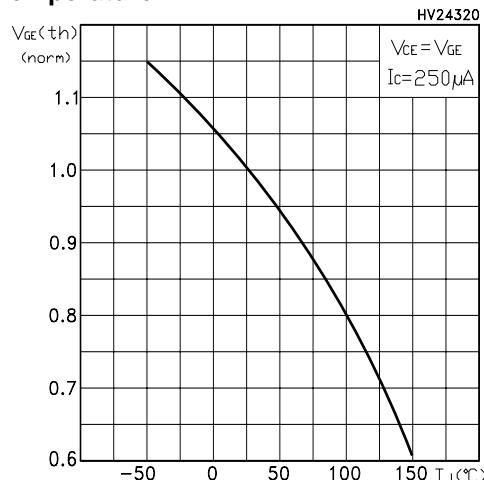
**Figure 9: Transconductance**



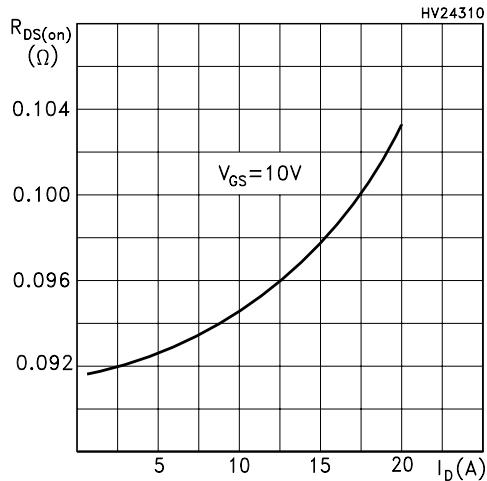
**Figure 10: Gate Charge vs Gate-source Voltage**



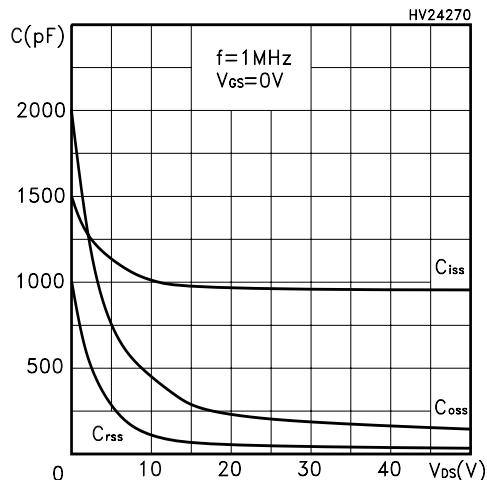
**Figure 11: Normalized Gate Threshold Voltage vs Temperature**



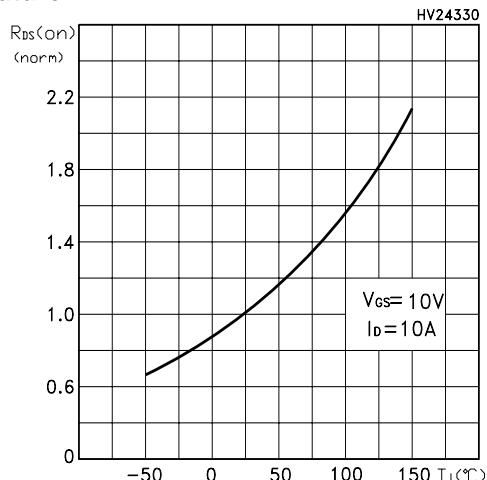
**Figure 12: Static Drain-source On Resistance**



**Figure 13: Capacitance Variations**



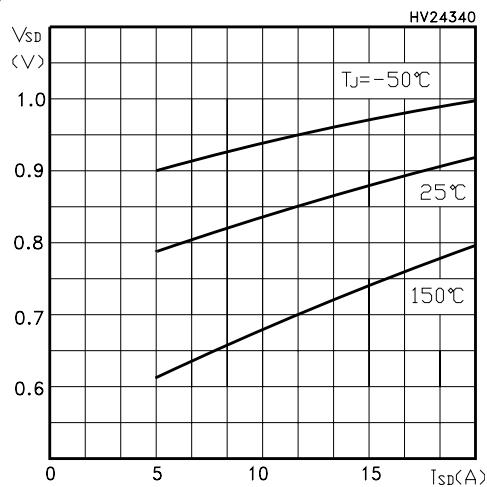
**Figure 14: Normalized On Resistance vs Temperature**



## **STP20N20 - STF20N20 - STD20N20**

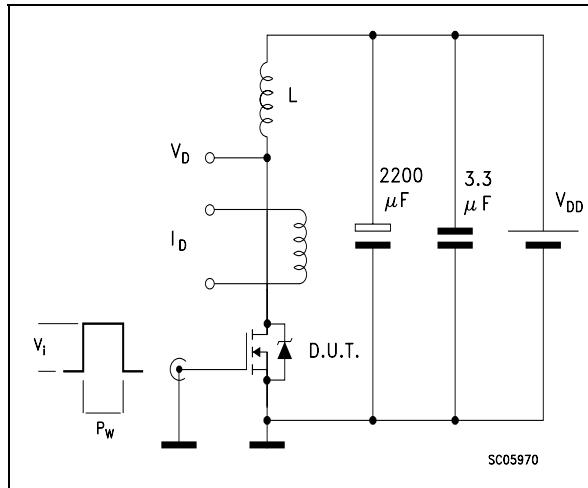
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**Figure 15: Source-Drain Forward Characteristics**

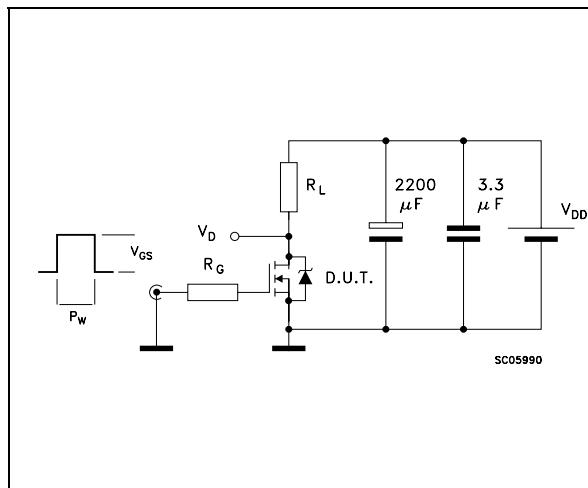


## STP20N20 - STF20N20 - STD20N20

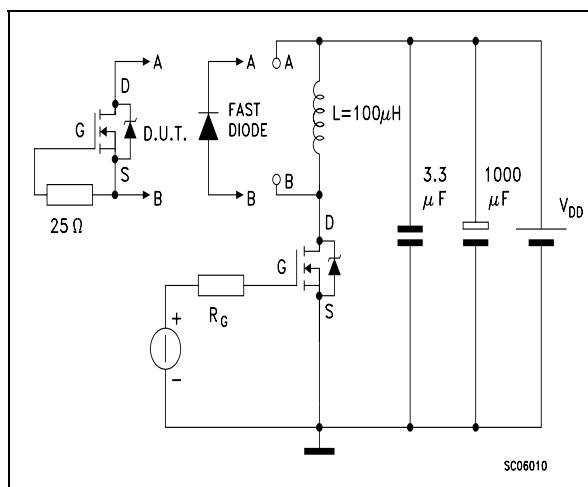
**Figure 16: Unclamped Inductive Load Test Circuit**



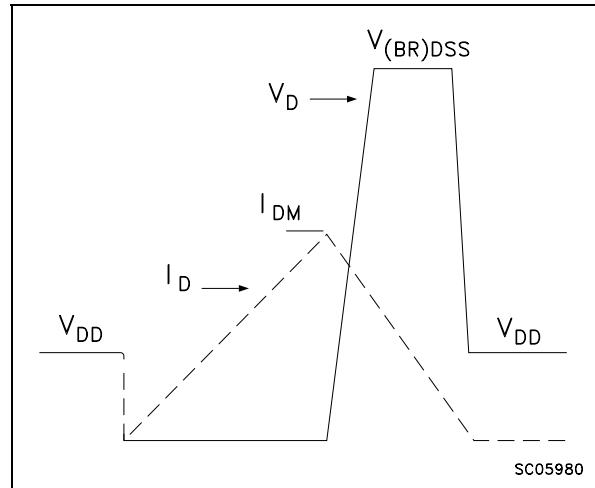
**Figure 17: Switching Times Test Circuit For Resistive Load**



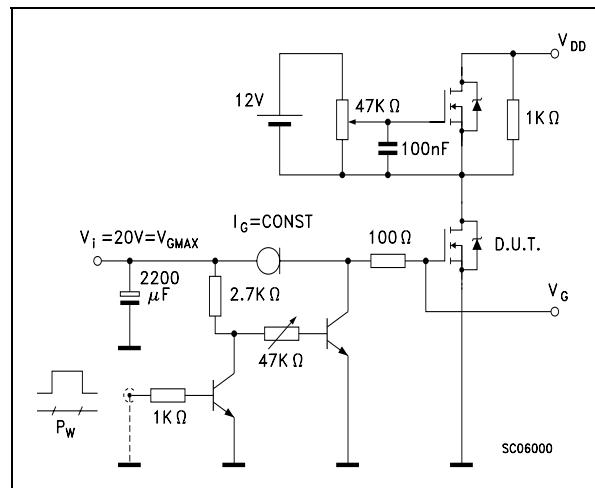
**Figure 18: Test Circuit For Inductive Load Switching and Diode Recovery Times**



**Figure 19: Unclamped Inductive Wafeform**



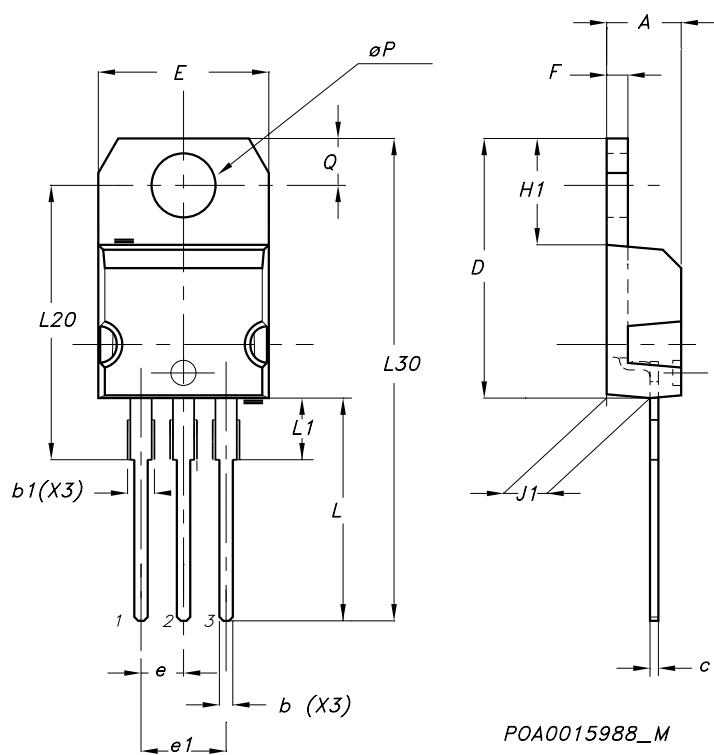
**Figure 20: Gate Charge Test Circuit**



**STP20N20 - STF20N20 - STD20N20**

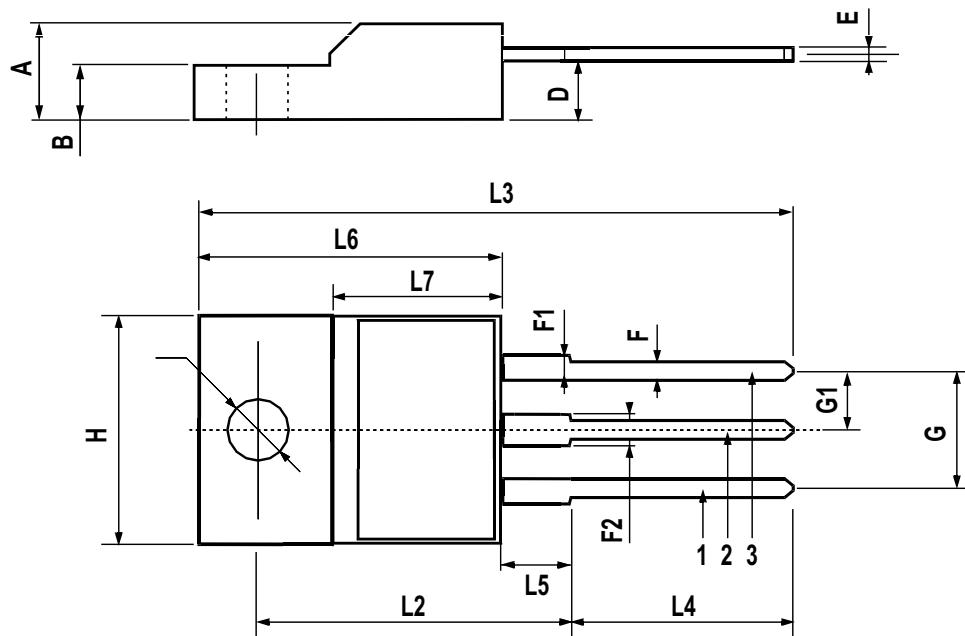
**TO-220 MECHANICAL DATA**

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
$\phi P$	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



**TO-220FP MECHANICAL DATA**

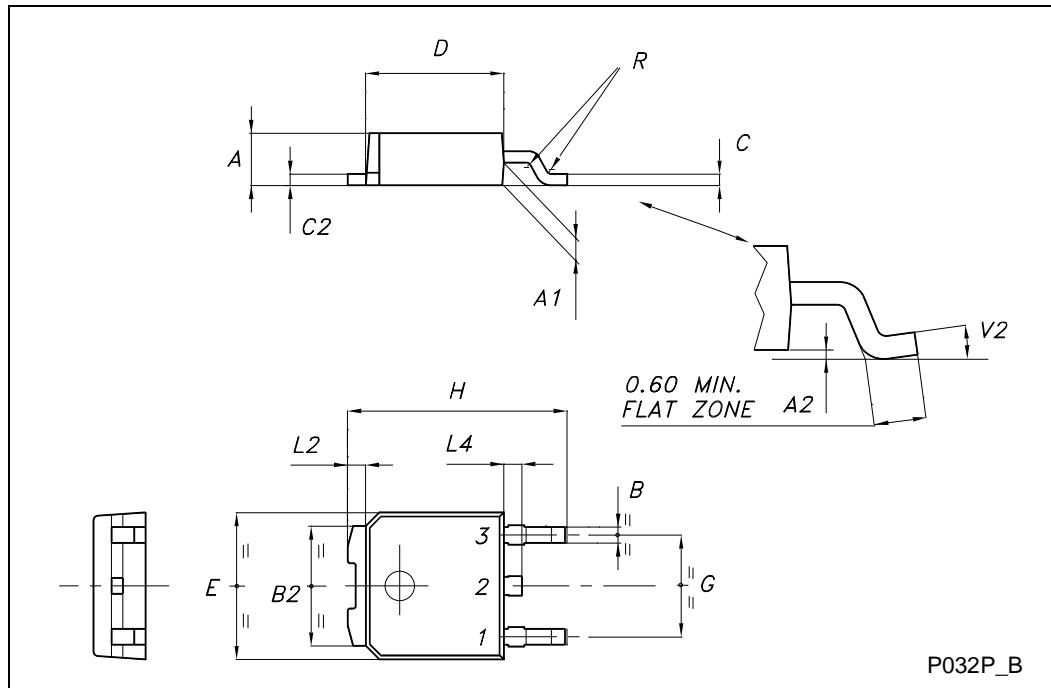
DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



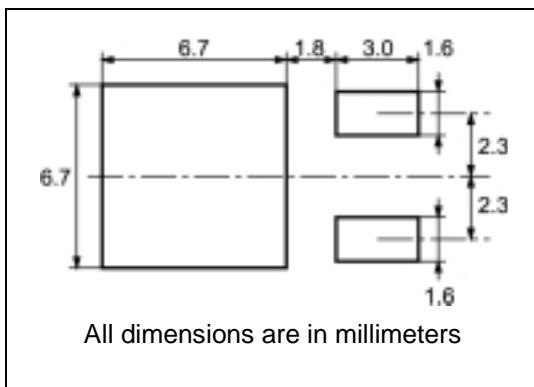
## STP20N20 - STF20N20 - STD20N20

### TO-252 (DPAK) MECHANICAL DATA

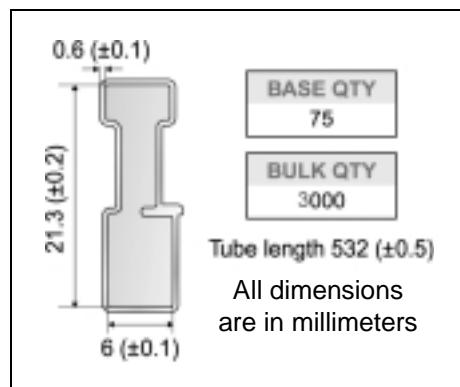
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
B	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
C	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



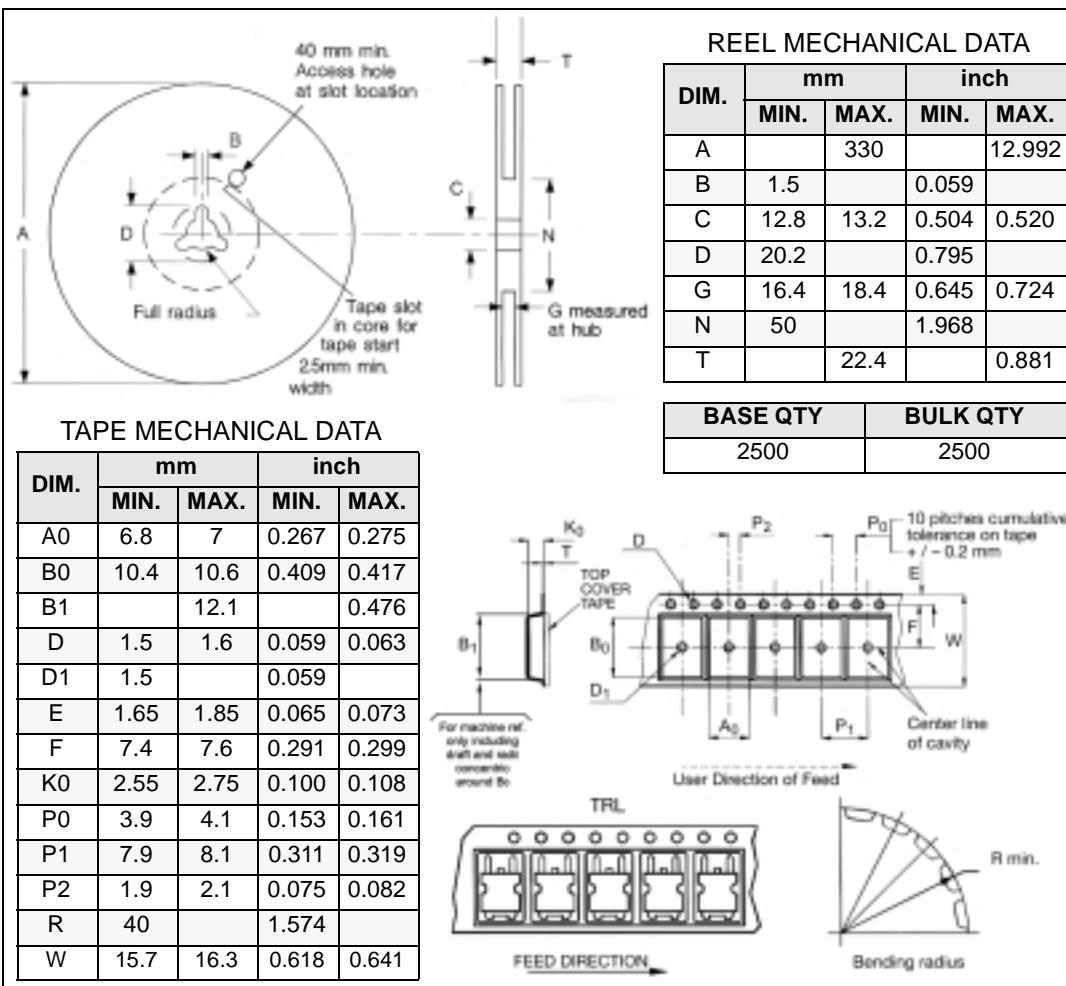
**DPAK FOOTPRINT**



**TUBE SHIPMENT (no suffix)\***



**TAPE AND REEL SHIPMENT (suffix "T4")\***



\* on sales type

## **STP20N20 - STF20N20 - STD20N20**

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**Table 9: Revision History**

Date	Revision	Description of Changes
06-Dec-2004	1	Data Brief
07-Dec-2004	2	First Revision
12-Jan-2005	3	Final datasheet

## **STP20N20 - STF20N20 - STD20N20**

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